This certificate is granted and awarded by the authority of the Nadcap Management Council to:

Benchmark Electronics, Inc.

3535 Technology Dr NW
Rochester, MN 55901
United States

This certificate demonstrates conformance and recognition of accreditation for specific services, as listed in www.eAuditNet.com on the Qualified Manufacturers List (QML), to the revision in effect at the time of the audit for:

Electronics

Certificate Number: 8778163871
Expiration Date: 31 October 2018

Joseph G. Pinto
Executive Vice President and Chief Operating Officer

SCOPE OF ACCREDITATION

Electronics

Benchmark Electronics, Inc.
3535 Technology Dr NW
Rochester, MN 55901

This certificate expiration is updated based on periodic audits. The current expiration date and scope of accreditation are listed at: www.eAuditNet.com - Online QML (Qualified Manufacturer Listing).

In recognition of the successful completion of the PRI evaluation process, accreditation is granted to this facility to perform the following:

AC7120 Rev D - Nadcap Audit Criteria for Circuit Card Assemblies (to be used on audits before 9 April 2017)

07– CAD/CAM Data
08– Electrostatic Discharge (ESD)
09– Material Handling
10– Moisture Sensitive Components and Materials
11– Re–Packaging
12.1– Programming: Component Programming (Prior Assembly)
12.2– Programming: Circuit Card Assembly Programming
13– Electronic Component Preparation For Preassembly Process
14– Stencil Printing
15.1– Part Placement: General
15.2– Part Placement: Manual
15.4– Part Placement: Automated Part Placement
15.5– Part Placement: Build through / Build Short
16.1– In–Process Verification / Inspection: General
16.2– In–Process Verification / Inspection: Visual
16.3– In–Process Verification / Inspection: AOI
16.4– In–Process Verification / Inspection: X–Ray
17– Bonding
18.1– Assembly Soldering Processes: General
18.2– Assembly Soldering Processes: Reflow Soldering
18.3– Assembly Soldering Processes: Wave Soldering
18.4– Assembly Soldering Processes: Selective Soldering
18.5– Assembly Soldering Processes: Hand Soldering

18.7– Lead–Free Soldering
19.1– Secondary Assembly: Mechanical Part Installation
19.2– Secondary Assembly: Wire Cutting & Stripping
19.3– Secondary Assembly: Jumper Wire Installation
19.5– Secondary Assembly: Compliant Pin (Press Fit) Connector Installation
20– Cleanliness
21– Coating and Encapsulation
22.1– Final Tests: Environmental Stress Screening
22.2– Final Tests: Bed of Nails Testing
22.3– Final Tests: Flying Probe Testing
22.6– Final Tests: Functional Testing
23– Final Inspection
24– Rework